



Fast Diode Modules

AMKE 800-F17



Symbols and parameters			Values			Units	
			min.	typ.	max.		
V_{RRM}	Repetitive peak reverse voltage	T _j = 25°C		1700		V	
I_F	Forward current (actual value)	T _j = 175°C	T _C = 25°C T _C = 100°C	953 601		A A	
I_{FRM}	Repetitive peak forward current			1600		A	
I_{FSM}	Surge forward current	10 ms	T _j = 25°C T _j = 150°C	4160 3712		A A	
i²t	I ² t value, rating for fusing	10 ms	T _j = 25°C T _j = 150°C	86528 68895		A ² s A ² s	
V_F	Forward voltage	I _F = 800 A chiplevel	T _j = 25°C T _j = 150°C	2.00 2.15	2.40 2.57	V V	
V_{F0}	Forward threshold voltage	chiplevel	T _j = 25°C T _j = 150°C	1.32 1.08	1.56 1.22	V V	
r_F	On-state slope resistance, forward slope resistance	chiplevel	T _j = 25°C T _j = 150°C	0.86 1.34	1.05 1.69	mΩ mΩ	
I_R	Reverse current	V _R = V _{RRM}	T _j = 25°C T _j = 150°C		0.68 200	mA mA	
Q_{RR}	Reverse recovery charge	I _F = 800 A di/dt _{off} = 4000 A/μs V _R = 1200 V	T _j = 150°C		210	μC	
I_{RRM}	Peak reverse recovery current		T _j = 150°C		400	A	
t_{rr}	Reverse recovery time		T _j = 150°C		1.2	μs	
E_{rr}	Energy dissipation during reverse recovery		T _j = 150°C		140	mJ	
R_{th(j-c)}	Thermal resistance, junction to case	per diode			0.58	K/W	
R_{th(c-s)}	Thermal resistance, junction to heatsink	per diode/module (λ _{grease} =0.81 W/ (m*K))			0.045	K/W	
		per diode/module, pre-applied phase change			-	K/W	
L_{CE}	Parasitic collector-emitter inductance			15		nH	
R_{CC'+EE'}	Resistance of the interconnections	measured per switch	T _C = 25°C T _C = 125°C	0.23 0.3		mΩ mΩ	
T_j	Junction temperature			-40		+175	°C
T_{stg}	Storage temperature range			-40		+125	°C
V_{isol}	Insulation test voltage (r.m.s.)	a.c. 50 Hz; r.m.s.;	1 s 1 min		4800 4000		V V
M_s	Mounting torque on heatsink			3		5	Nm
M_t	Mounting torque for terminals			2.5		5	Nm
a	Maximum allowable acceleration				5*9.81		m/s ²
W	Weight				330		g

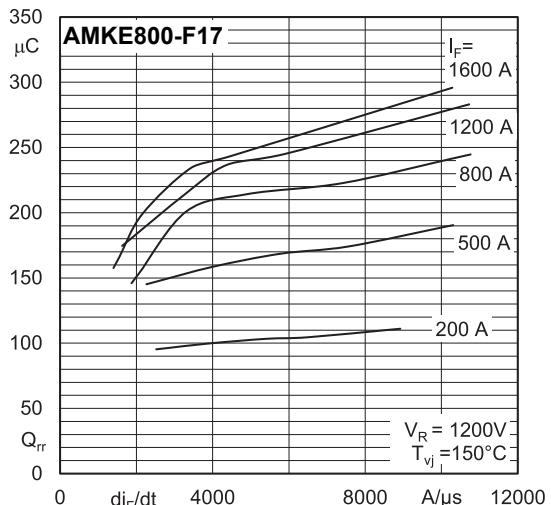


Fig. 1: Typ. recovery charge vs. current decrease

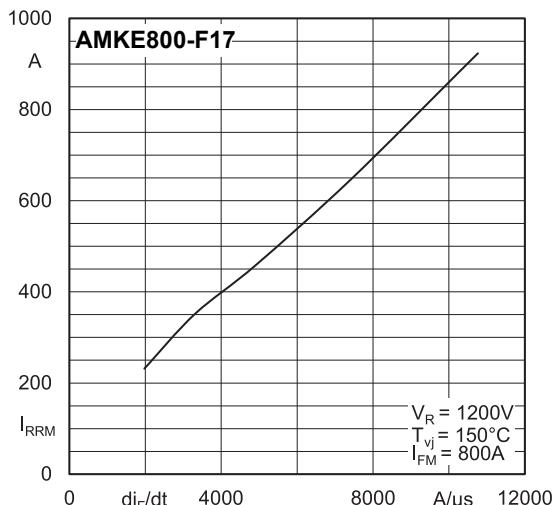


Fig. 2: Peak recovery current vs. current decrease

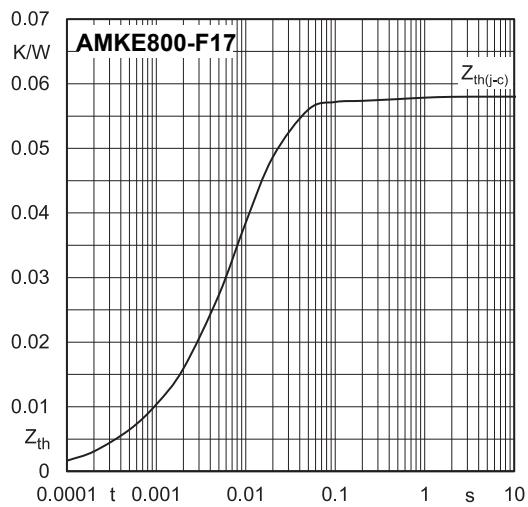


Fig. 3: Transient thermal impedance vs. time

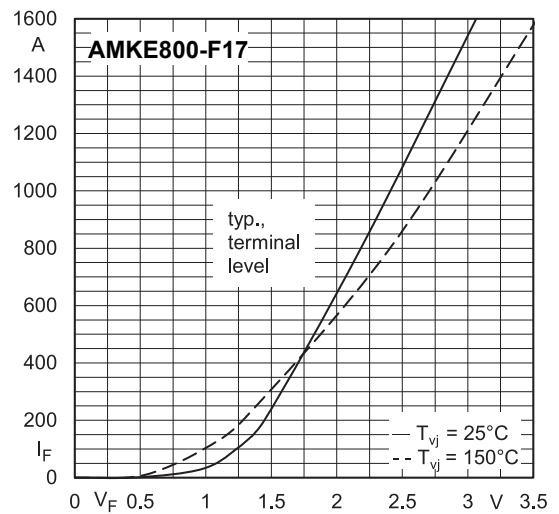


Fig. 4: Forward characteristics

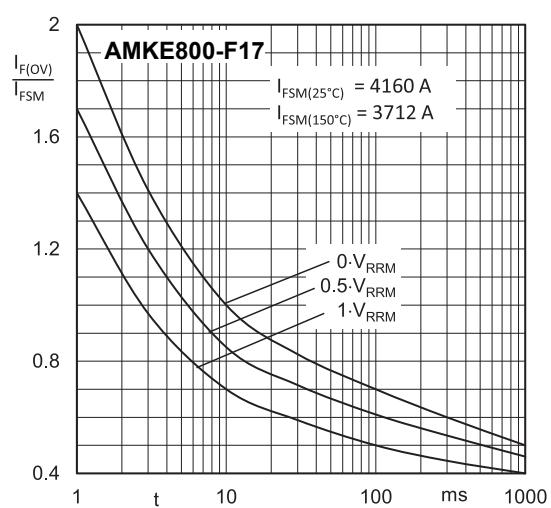


Fig. 5: Surge overload current vs. time

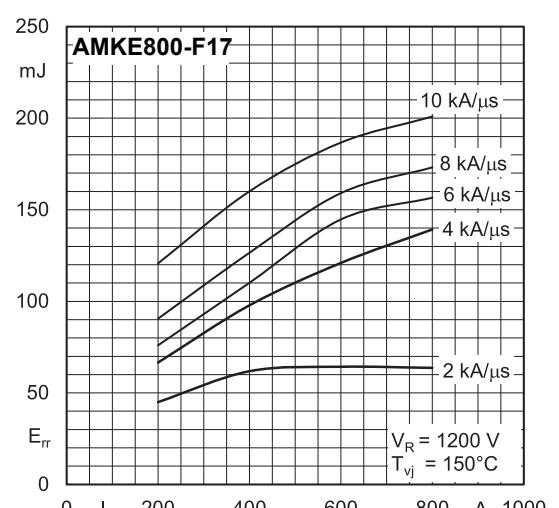
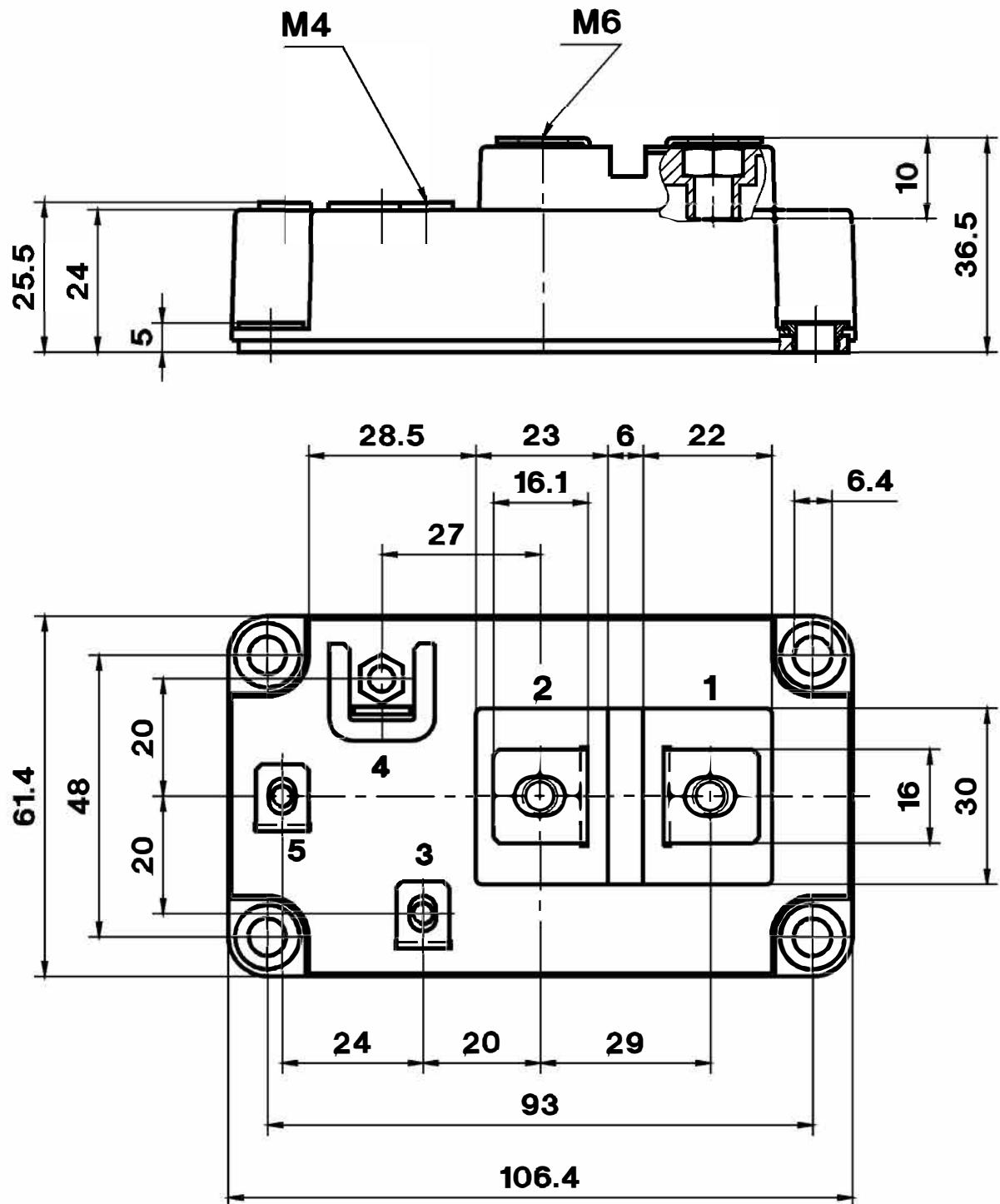


Fig. 6: Typ. turn-off energy dissipation per pulse

DIMENSIONS

CASED59



TOPOLOGY OF INTERNAL CONNECTION

